FIG.1

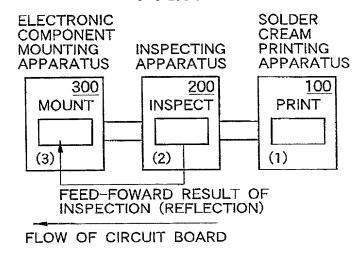
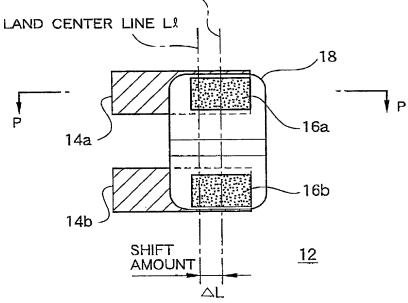
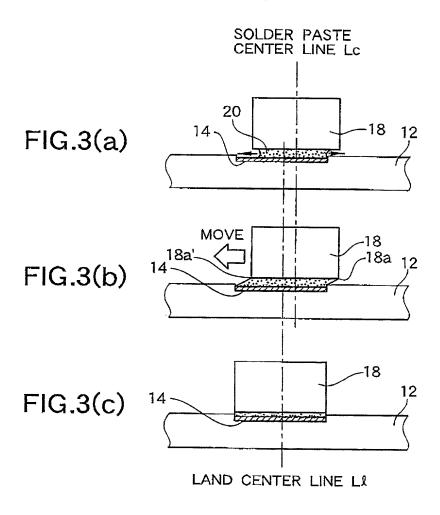
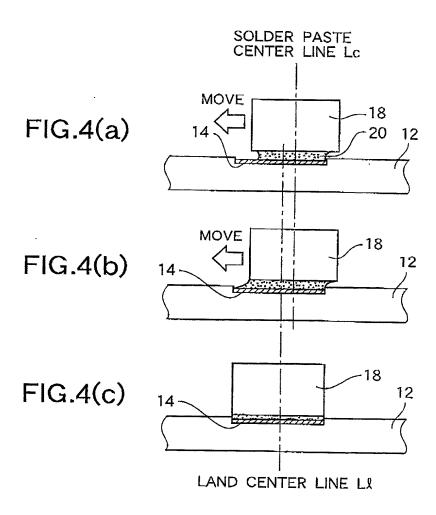


FIG.2

SOLDER PASTE CENTER LINE LC ELECTRONIC COMPONENT CENTER LINE Lp







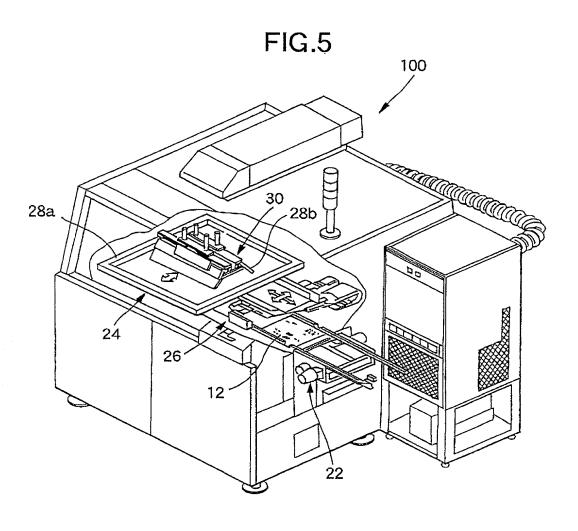
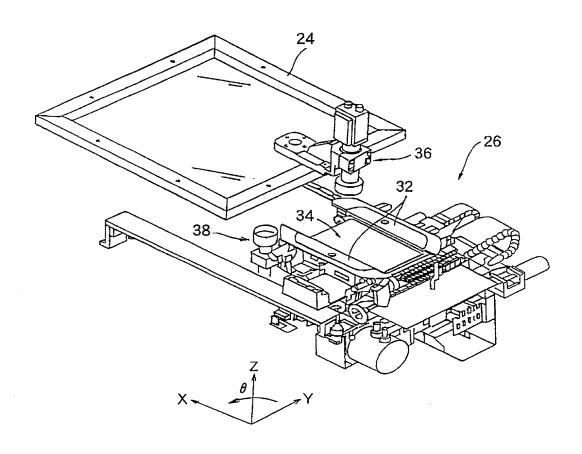
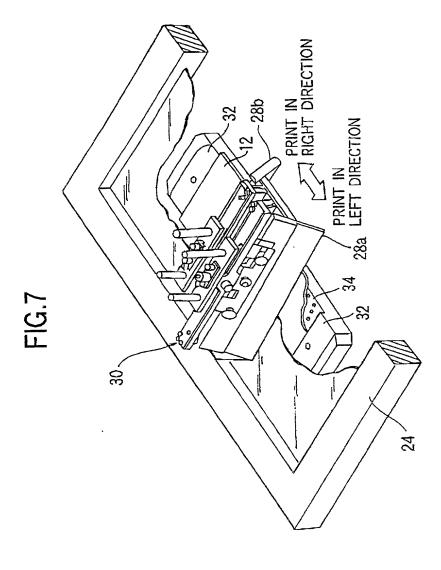
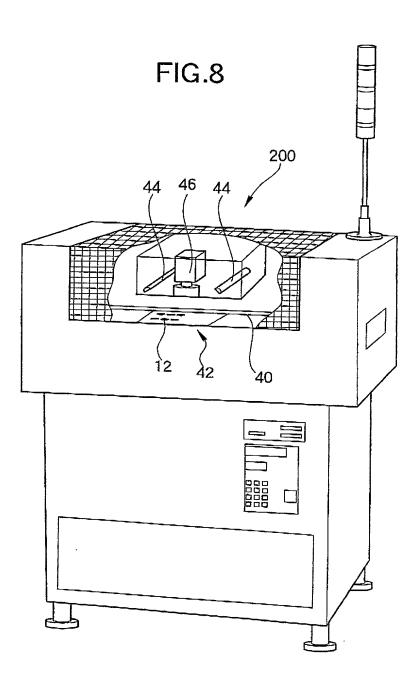
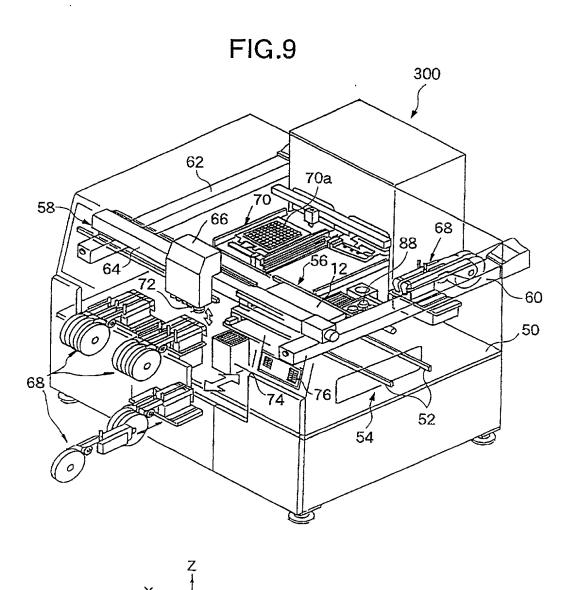


FIG.6









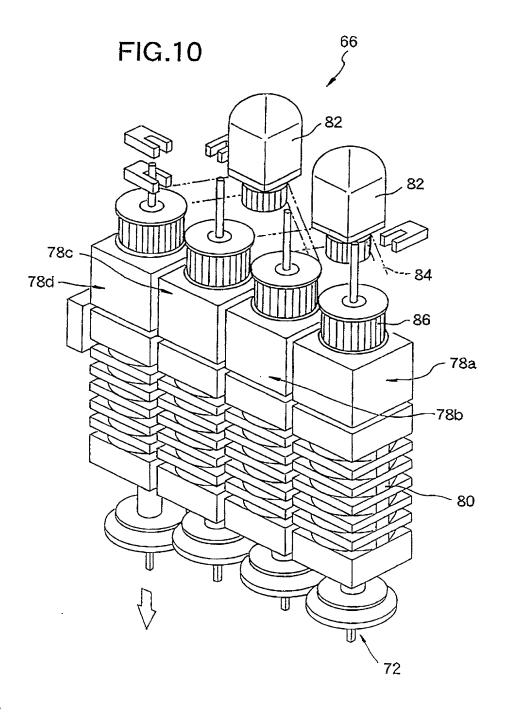


FIG.11

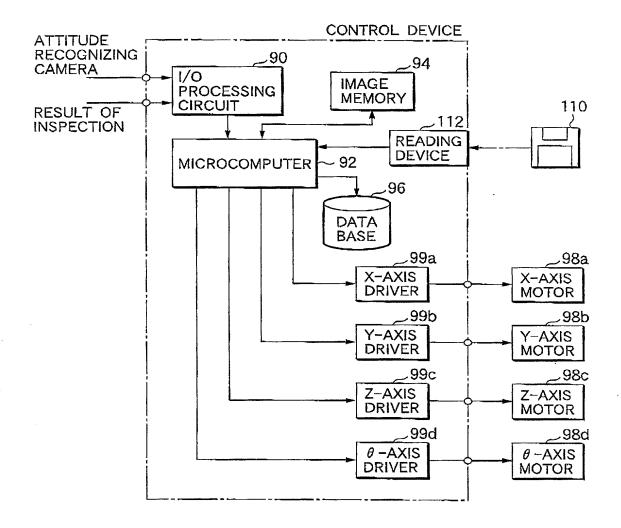


FIG.12

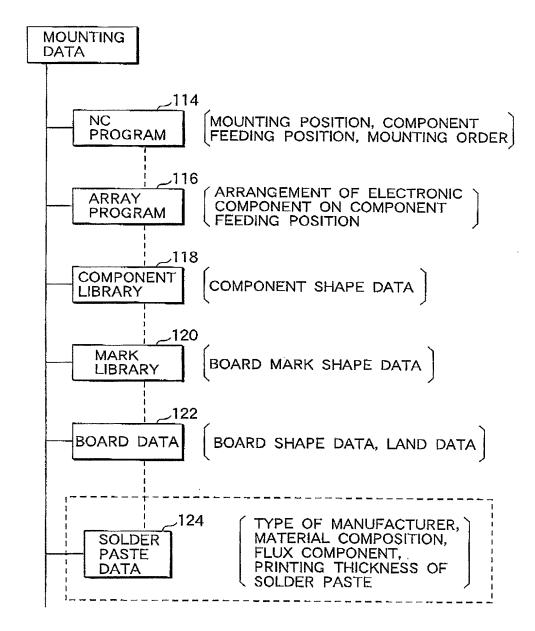


FIG.13

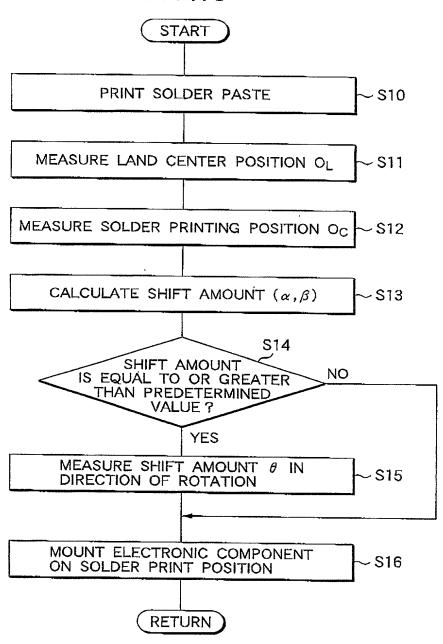


FIG.14

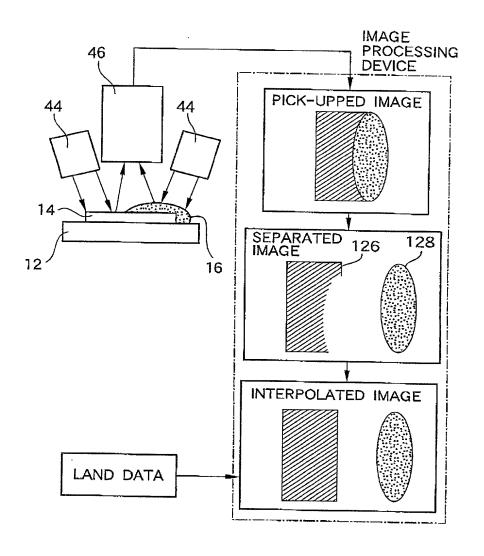
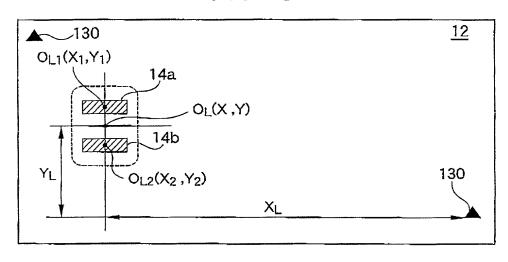
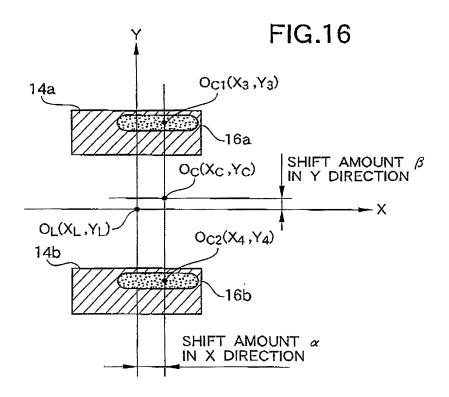
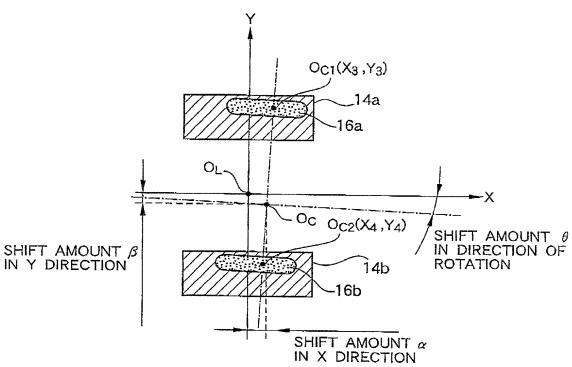


FIG.15









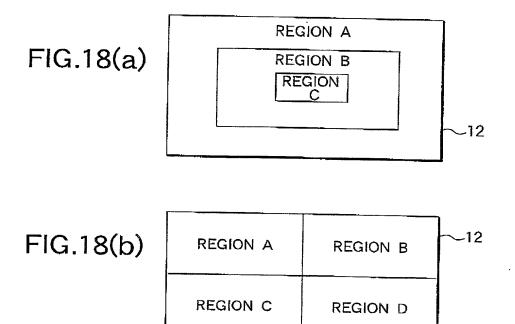
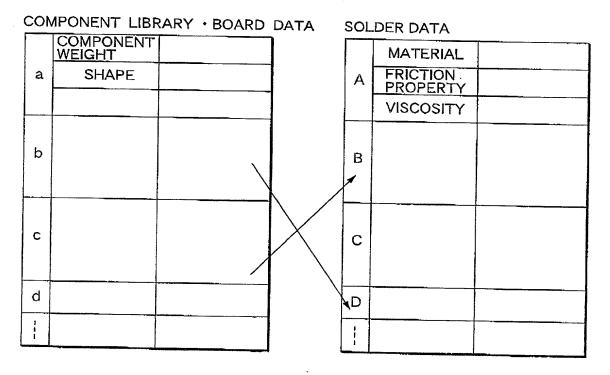
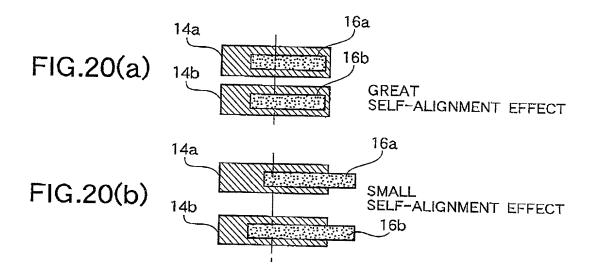
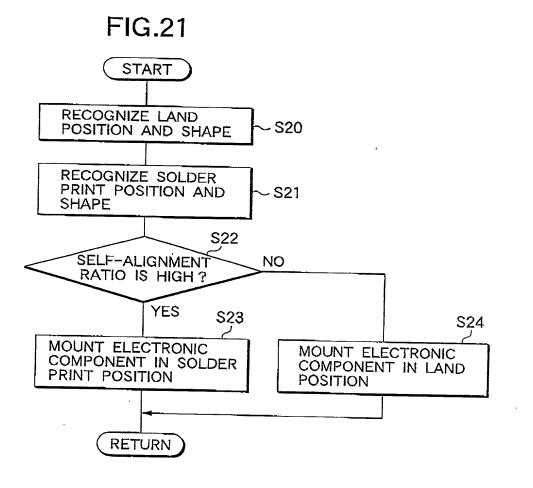
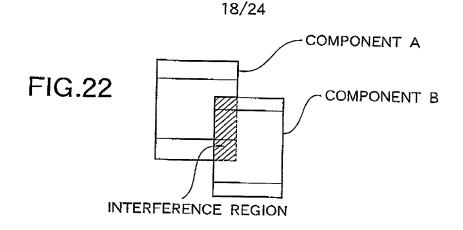


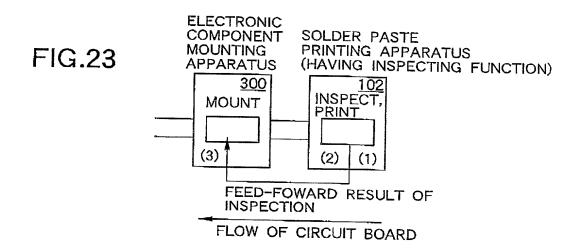
FIG.19











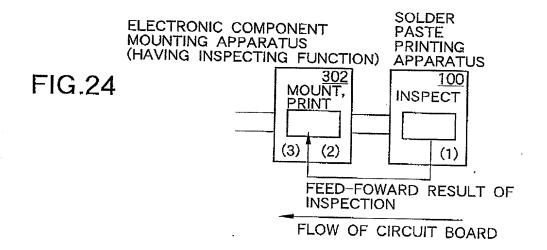
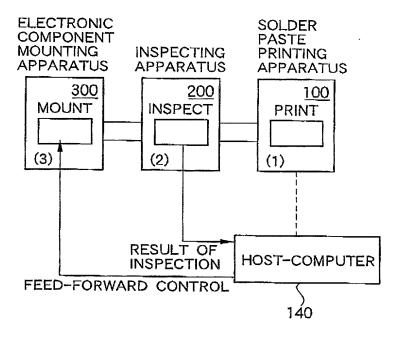


FIG.25



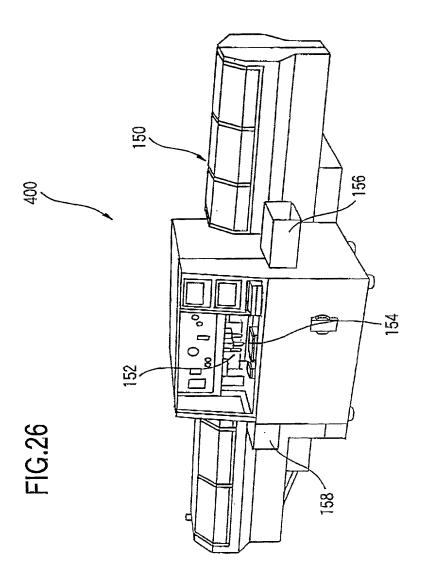


FIG.27

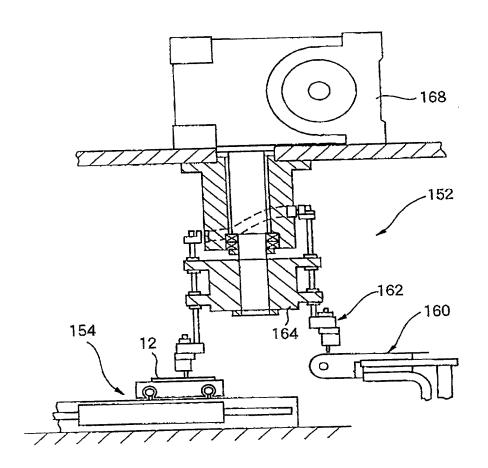


FIG.28(a) **REFLOW** MOUNTING STEP **PRINTING** STEP STEP PRINT ON LAND MOUNT WITH SHIFT FROM LAND POSITION REFERENCE FIG.28(b) MOUNT ON PRINT WITH PRINT POSITION SHIFT FROM LAND REFERENCE FIG.28(c) SELF-ALIGNMENT RATIO (%) 100 80 60 40 OMOUNT WITH SHIFT FROM LAND (a) 20 MOUNT ON PRINT POSITION REFERENCE (b) 50 60 70 80 90 100 30 40 10 20 SHIFT AMOUNT Δ L (μ m)

FIG.29

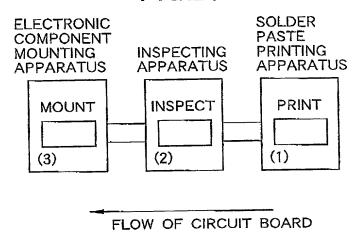


FIG.30(a)

FIG.30(b)

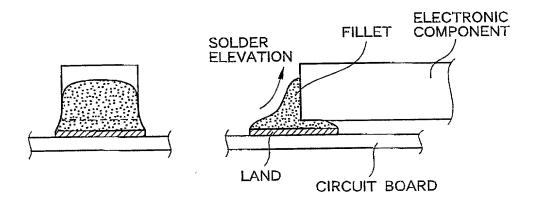


FIG.31(a)

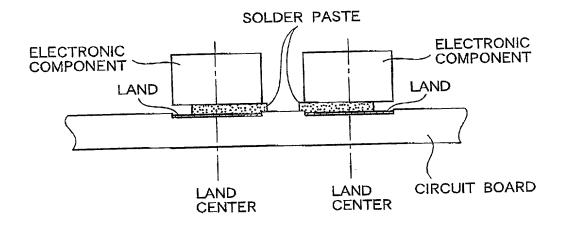


FIG.31(b)

